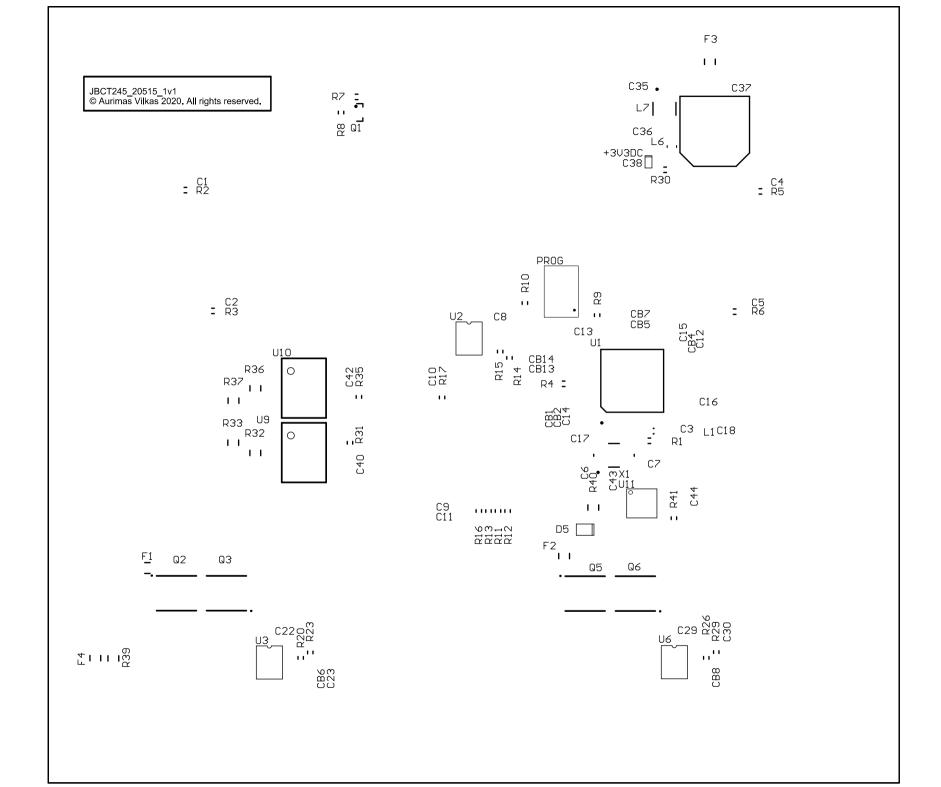
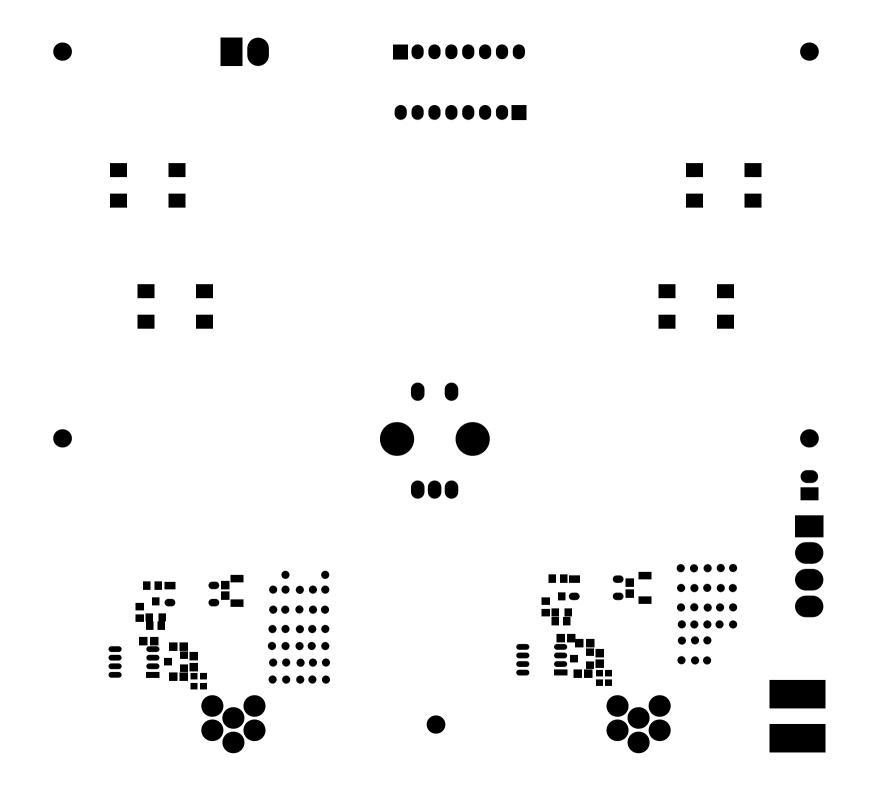
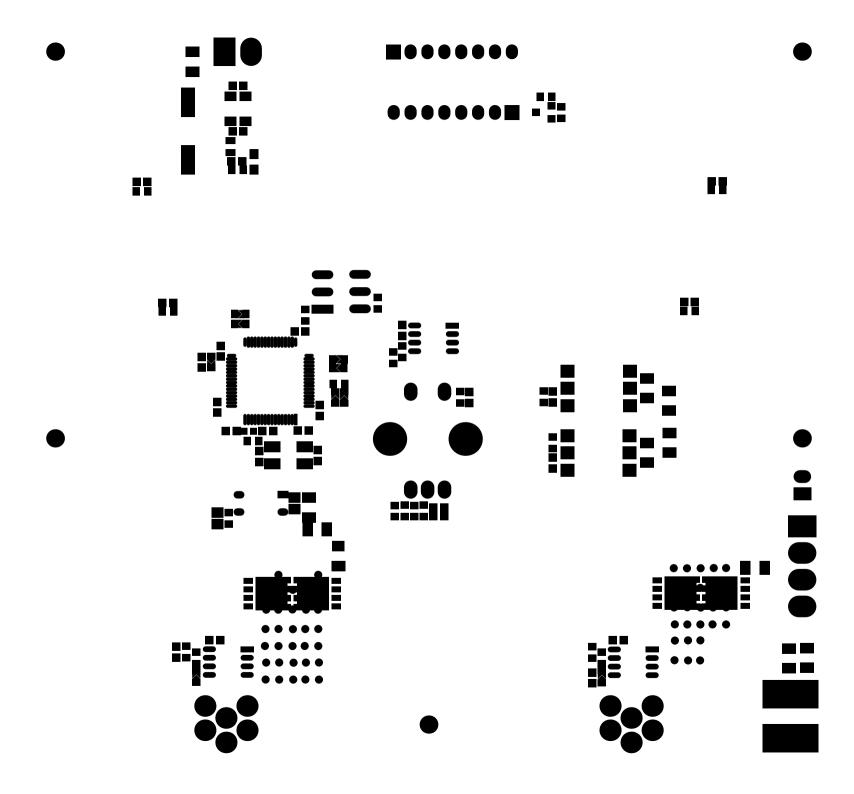


BTN_OK	JBCT245_20515_1v1 © Aurimas Vilkas 2020. All rights reserved.  BTN_UP
BTN_ON∕OFF	BTN_DN
R25 U7 E R28 E C31 E D4 C34 T T	R19

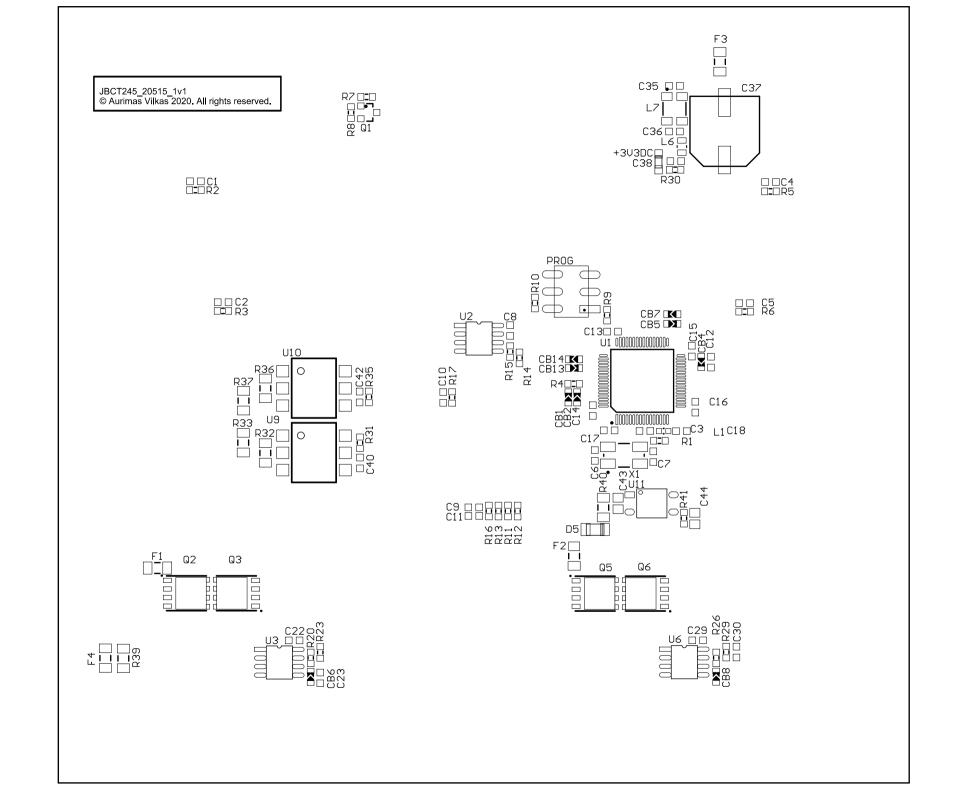






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Quan	Comment	Description	Supplier 1	Supplier Part Number 1	Footprint	Designator
		1N4148W - Small Signal Diode, Single, 75 V, 150 mA, 1 V, 4 ns, 400 mA	Supplier 1	2677464		
1	1N4148W Sleep_Det	400 mA 2 header, 2.54mm 24LC256-E/SN - EEPROM. 256	Farnell	2677464 1248140	SOD-123F HDR1X2_2.54mm	D5 SLPD
1	24LC256-E/SN	Kbit, 32K x 8bit, Serial I2C (2- Wire), 400 kHz, SOIC, 8 Pins	Farnell	1579573	SOIC-8	U2
		0603N180J500CT - SMD Multilayer Ceramic Capacitor, 0603 [1608 Metric], 18 pF, 50 V,				
2	18p	± 5%, COG / NP0 62409-1 - PCB Terminal, 6.35mm x 0.81mm, 0.25" x	Farnell	2496890	CAPC1608N	C6, C7
2	Blade Header	0.032", Brass, 1.4 mm, Tin 1241050-3 - Board-To-Board	Farnell	892609	Blade header	Earth1, Earth2
		Connector, 2.54 mm, 6 Contacts, Header, AMPMODU MOD II Series, Surface Mount,				
1	PROG	2 Rows 744235900 - Filter, Line, Common Mode, 300 nH, WE-	Farnell	9689567	B6B_SMT	PROG
1	300nH 2A	CNSW Series, 90 ohm, 2 A, 4.5mm x 3.2mm x 2.8mm ACS711KLCTR-12AB-T - Current	Farnell	2249865	1812_CM_WE	L7
2	ACS711KLCTR-12AB-	Sensor, Overcurrent Fault, 4 mA, 100 kHz, SOIC, 8 Pins, 3 V, 5.5 V	Farnell	2057423	SOIC-8	112 114
	1	B8B-XH-A (LF)(SN) - Wire-To- Board Connector, Vertical, 2.5	ramen	2057425	3010-6	U3, U6
1	ST7735 1.44inch	mm, 8 Contacts, Header, XH Series, Through Hole, 1 Rows B8B-XH-A (LF)(SN) - Wire-To-	Farnell	1516284	B8B-XH-A (LF)(SN)	ST7735 1.44inch
1	ST7920 GLCD (128×64)	Board Connector, Vertical, 2.5 mm, 8 Contacts, Header, XH Series, Through Hole, 1 Rows	Farnell	1516284	B8B-XH-A (LF)(SN)	ST7920 GLCD (128×64)
	(	BLM18AG601SN1D - Ferrite Bead, 0603 [1608 Metric], 600 ohm, 500 mA, BLM18A Series,				(,
1	BLM18A	0.38 ohm, ± 25% BLM18PG471SN1D - Ferrite	Farnell	1515679	0603L	L1
4	BLM18PG471SN1D	Bead, 0603 [1608 Metric], 470 ohm, 1 A, BLM18P Series, 0.2 ohm, ± 25%	Farnell	1515745	LL0603\2P	L2, L3, L4, L5
		BLM21PG221SN1D - Ferrite Bead, 0805 [2012 Metric], 220 ohm, 2 A, BLM21P Series, 0.045				
1	220R 2A	ohm, ± 25% BSC070N10NS3GATMA1 - Power MOSEFT N Channel 100	Farnell	1515661	LL0805\2P	L6
4	BSC070N10NS3GAT MA1	V, 90 A, 0.0063 ohm, TDSON, Surface Mount	Farnell	2443421	PG-TDSON-8	Q2, Q3, Q5, Q6
2	12V	BZT55C12-GS08 - Zener Single Diode, 12 V, 500 mW, SOD-80 (MiniMELF), 5 %, 2 Pins, 175 °C	Farnell	2690028	SOD-80C	D1, D3
3	Closed	Circuit Breaker			CB_0603	CB2, CB5, CB14 CB1, CB4, CB6,
6	Open	Circuit Breaker CL10A475KQ8NNNC - SMD Multilayer Ceramic Capacitor,			CB_0603	CB7, CB8, CB13
1	4u7F	4.7 μF, 6.3 V, 0603 [1608 Metric], ± 10%, X5R, CL Series CL21B105KBFNNNE - SMD	Farnell	3013399	CAPC1608N	C12
2	1uF 50V	Multilayer Ceramic Capacitor, 1 μF, 50 V, 0805 [2012 Metric], ± 10%, X7R, CL Series	Farnell	3013482	CAPC2012N	C43, C44
1	HDR1X2	CONNECTOR, 2 way, HEADER, THT, 3.96MM,10A,250Vac	Farnell	9492003	HDR1X2_3M96V	DC_IN
1	HDR1X4	CONNECTOR, 4 way, HEADER, THT, 3.96MM,10A,250Vac CRGCQ1206J10M - SMD Chip	Farnell	9492020	HDR1X4_3M96V	AC_IN1
1	10M	Resistor, 1206 [3216 Metric], 10 Mohm, CRGCQ Series, 200 V, Thick Film, 250 mW	Farnell	2861974	RESC3216N	R39
	TOW	CRGH0603F1K0 - SMD Chip Resistor, 1 kohm, CRG Series,	i airieii	2001774	RESUSZ TOW	K37
3	1k	50 V, Thick Film, 0603 [1608 Metric], 200 mW CRGH0603F220R - SMD Chip	Farnell	2332003	RESC1608N	R8, R22, R28
3	220R	Resistor, 220 ohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200 mW	Farnell	2331993	RESC1608N	R7, R21, R27
1	8 MHz	CRYSTAL, 8M, 18PF CL, 6X3.6MM SMT	Farnell	1611803	2SMX-3SMXB	X1
		FMMT493ATA - Bipolar (BJT) Single Transistor, NPN, 60 V,				
3	FMMT493ATA	150 MHz, 500 mW, 1 A, 300 hFE FSM2JRT - Tactile Switch, Non	Farnell	2061448	SOT23-3	Q1, Q4, Q7 BTN_DN, BTN_OK,
4	Button	Illuminated, 24 V, 50 mA, 225 gf, PC Pin, FSM Series H11AA1SR2M - Optocoupler,	Farnell	2610957	PB-6X6mm	BTN_ON/OFF, BTN_UP
2	H11AA1SR2M	Transistor Output, 1 Channel, Surface Mount DIP, 6 Pins, 60	Farnell	2322525	SMDIP-6	U9, U10
		mA, 7.5 kV, 20 % KPT-2012SGC - LED, Low Power, Green, SMD, 2mm x				
1	Green LED	1.25mm, 20 mA, 2.2 V, 568 nm MAX31855KASA+T - Temperature Sensor IC,	Farnell	2099239	LED_GRN	+3V3DC
2	MAX31855KASA+T	Thermocouple, Digital, ± 2°C, - 200 °C, 1350 °C, NSOIC, 8 Pins	Farnell	2515622	SOIC-8	U5, U8 C3, C8, C13,
		MC0805B104K250CT - SMD				C14, C15, C16, C17, C18, C21, C22, C24, C25,
21	100nF	Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0805 [2012 Metric], ± 10%, X7R, MC Series	Farnell	1759166	CAPC1608N	C27, C28, C29, C31, C32, C34, C35, C36, C38
		MCCFB1206TFF/1.5 - Fuse, Surface Mount, 1.5 A, 32 V, Fast				
2	1.5A Fuse	Acting, 1206 MCCFB1206TFF/8 - Fuse, Surface Mount, 8 A, 32 V, Fast	Farnell	1652166	1206F	F3, F4
2	8A	Acting, 1206 MCHVR03JTEX1000 - SMD Chip	Farnell	2850026	1206F	F1, F2
	4000	Resistor, High Voltage, 100 ohm, HVR Series, 200 V, Thick Film, 0603 [1608 Metric], 100			arras ( an )	Dog
2	100R	mW MCSR06X68R0FTL - SMD Chip Resistor, 68 ohm, MCSR 06	Farnell	2825696	RESC1608N	R23, R29
3	68R	Series, 75 V, Ceramic, 0603 [1608 Metric], 100 mW	Farnell	2074301	RESC1608N	R19, R25, R30
		MCU0603R103KCT - SMD Multilayer Ceramic Capacitor, 10000 pt. 50 V 0603 11608				C1, C2, C4, C5, C9, C10, C11, C23, C26, C30
12	10.5	10000 pF, 50 V, 0603 [1608	Farnell	9406182	CAPC1608N	C23, C26, C30, C33, C40, C42
13	10nF	Metric], ± 10%, X7R, MCU Series MCVVT025M471GB3L - SMD				1
13	470uF 25V	MCVVT025M471GB3L - SMD Aluminium Electrolytic Capacitor, Radial Can - SMD, 470 µF, 25 V, VT, V-Chip Series	Farnell	2611378	10X10.5	C37
		MCVVT025M471GB3L - SMD Aluminium Electrolytic Capacitor, Radial Can - SMD, 470 μF, 25 V, VT, V-Chip Series MCWF12P1501FTL - SMD Chip Resistor, 1206 [3216 Metric], 1.5		2611378	10X10.5	C37 R32, R33, R36,
		MCVVT025M471GB3L - SMD Aluminium Electrolytic Capacitor, Radial Can - SMD, 470 μF, 25 V, VT, V-Chip Series MCWF12P1501FTL - SMD Chip		2611378 2694448	10X10.5 RESC3216N	R32, R33, R36, R37, R40 R2, R3, R5, R6,
1	470uF 25V	MCVVT025M471G83L - SMD Alurinium Electrolytic Capacitor, Radial Can - SMD, 470 µF, 25 V, VT, V-Chip Serles MCVVF12P1501FT - SMD Chip Resistor, 1206 [3216 Metric], 1.5 kohm, MCWT12P5 Serles, 200 V, Thick Film, 500 mW	Farnell			R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17,
1	470uF 25V	MCCVT025M471G881 - SMD Aluminium Electrolytic Capacitor, Radial Can - SMD, 470 pf. 25 v. V. C-hip Series MCWF1291501FIT SMD Chip Resistor, 120 E216 Metriq. 15 Kohm, MCWF12P Series, 200 v. Thick Film, S00 only MCWR06X1002FIT SMD Chip Resistor, 0603 [1608 Metriq.] 10 kohm, MCWR Series, 50 v, Thick Film, 500 series, 50 v, Thick Film, 500 series, 50 v,	Farnell			R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14,
1	470uF 25V 1k5 1/2W	MCVVT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 pf. 25. V/Y. C-Chip Series MCWF12915G1F1L - Mehrid, 15. MCWF12915G1F1L - SMD Chip Resistor, 0603 [1608 Metrid, 10 kohm, MCWF2 Series, 200 V, Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Metrid, 10 kohm, MCWF2 Series, 50 V, Thick Film, 100 mW MCVMR06X1003FTL - SMD Chip Resistor, 0603 [1608 Metrid, 10 kohm, MCWR05X1003FTL - SMD Chip Resistor, 0603 [1608 Metrid, 10 kohm, MCWR05X1003FTL - SMD Chip Resistor, 0603 [1608 Metrid, 10 kohm, MCWR05X1003FTL - SMD Chip Resistor, 0603 [1608 Metrid, 10 kohm, MCWR Series, 50 V,	Farnell Farnell Farnell	2694448 2447230	RESC3216N RESC1608N	R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41
1	470uF 25V 1k5 1/2W	MCVVT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 pf. 25 v. V; C-Chip Series MCWF12915G1F1T SMD Chip Resistor, 1206 Egot Merind; 15 Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Merind; 10 kohm, MCWR Series, 50 v. Thick Film, 100 mW MCVR06X1002FTL - SMD Chip Resistor, 0603 [1608 Merind; 10 MCVR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merind; 10 MCVR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merind; 10 MCVR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merind; 10 MCVR06X1004 Series, 50 v. Thick Film, 100 mW	Farnell Farnell	2694448	RESC3216N	R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31,
1 5	470uF 25V 1k5 1/2W	MCWT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 µF. 25 V. V. Chip Series MCWF12P1501FIT - SMD Chip Resistor, 1206 g216 Metricl, 15 kohm, MCWF12P Series, 200 V. Thick Film, 500 mW MCWR0641002FIT - SMD Chip Resistor, 0003 [1608 Metricl, 10 hom, McWR Series, 50 V. Thick Film, 100 mW MCWR06A1003FIT - SMD Chip Resistor, 0003 [1608 Metricl, 10 hom, McWR Series, 50 V. Thick Film, 100 mW MCWR06A1003FIT - TWS Dlode, NURS Series, 50 V. Thick Film, 100 mW NUP3 100 High Chip NUP3 Long MCWR Series, 50 V. Thick Film, 00 mW NUP3 100 High Chip NUP3 Long MCWR Series, 50 V. Thick Film, 00 mW NUP3 100 High Galler Chip NUP3	Farnell Farnell Farnell	2694448 2447230	RESC3216N RESC1608N	R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41
18	470uF 25V  1k5 1/2W  10k  100k  NUP210SLT1G	MCVVT025M471G881 - SMD Aluminium Electrolytic Capacitor, Radial Can - SMD, 470 pf. 25 v. V. C-hip Series MCWF1291501F1L - SMD Chip Resistor, 1206 2216 Metriq, 13 Kohrn, MCWF129 Series, 200 v. Thick Film, 500 mWy MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Metriq, 10 kohrn, MCWR Series, 50 v. Thick Film, 100 mWy MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Metriq, 10 Kohrn, MCWR Series, 50 v. Thick Film, 100 mWy MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Metriq, 10 MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Metrid, 10 MCWR06X103FTL - SMD Chip MCWR06X103FTL -	Farnell  Farnell  Farnell  Farnell	2694448 2447230 2447226RL 2101833	RESC3216N  RESC1608N  RESC1608N  SOT23-3	R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41 R1, R4
18	470uF 25V  1k5 1/2W  10k  100k  NUP2105LT1G	MCWY025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 µF, 28 V. V. O-thip Series MCWF1297501FTL - SMD Chip Resistor, 1206 2316 Metricl, 1.5 kohm, MCWF12P Series, 200 V. Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Metric], 100 kohm, MCWR Series, 50 V. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Metric], 100 kohm, MCWR Series, 50 V. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Metric], 100 kohm, MCWR Series, 50 V. Thick Film, 100 mW NUP2 Series, 50 V. Thick Film, 100 mW NUP2 Series, 50 V. Thick Film, 100 mW NUP2 Series, 5004 - Rotary ECT1R-4225F-50024 - Rotary ECT1R-4225F-50024 - Rotary ECT1R-4225F-50024 - Rotary Encoder, Mechanical, Incremental, 24 PPR, 24	Farnell Farnell Farnell	2694448 2447230 2447226RL	RESC3216N  RESC1608N  RESC1608N	R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41
18 2 2 2	470uF 25V  1k5 1/2W  10k  100k  NUP210SLT1G	MCVVT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 pf. 25 v. VV. Chip Series MCWF12915G1F1T SMD Chip Resistor, 1206 g216 Merinq, 13 Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 10 Kohm, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 10 No kohm, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 100 kohm, MCWR Series, 50 v. Thick Film, 100 mW MDP210ST1G - TVS Diode, NUP21 Series, Bidirectional, 22 v. 40 v. SOT-23, 3 Pins FECTIR-4225F-50024 - Rotary Encoder, Mechanical Momentary Push Wish Momentary Postics, Paries, Panel Mount Receptacle, 6 Contacts, Solder Pin	Farnell  Farnell  Farnell  Farnell	2694448 2447230 2447226RL 2101833	RESC3216N  RESC1608N  RESC1608N  SOT23-3	R32, R33, R36, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41 R1, R4
18 2 2 2	100k 100k NUP2105LT1G PEC11R-4225F- S0024	MCWT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 µF. 25 V. V. Chip Series MCWF1291501FIT - SMD Chip Resistor, 1206 £216 Metriq, 13 Kohm, MCWF12P Series, 200 V. Thick Film, 500 mW MCWR06X1002FIT - SMD Chip Resistor, 0603 [1608 Metrid, 10 Kohm, MCWR Series, 50 V. Thick Film, 500 mW MCWR06X1003FIT - SMD Chip Resistor, 0603 [1608 Metrid, 10 Kohm, MCWR Series, 50 V. Thick Film, 100 mW MCWR06X1003FIT - SMD Chip Resistor, 0603 [1608 Metrid, 10 MCWR06X1003FIT - WS Diode, NUP21 Series, 85024 - Rotary EPCT1R-4225FS0024 - Rotary EPCT1R-4225FS0024 - Rotary EPCT1R-4225FS0024 - Rotary EPCT1R-4225FS0024 - Rotary EPCT1R-4225F307 - Circuit Connector, RP Series, Panel Mount Receptacle, 6 Contacts, Solder Pin STM3274466FCT6 - ARM MCU, High Performance, STM32 Family STM3274 Series	Farnell  Farnell  Farnell  Farnell  Farnell	2694448 2447230 2447226RL 2101833 2381866	RESC3216N  RESC1608N  RESC1608N  SOT23-3  PEC12R-4000F-S000C,1	R32, R33, R36, R37, R40 R2, R8, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41
1 18 2 2 2 2	100k 100k NUP2105LT1G PEC11R-4225F- S0024	MCWT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 pf. 25 v. V. C-hip Series MCWF12975G7FTL - SMD Chip Resistor, 1206 E216 Metriq, 13 Kohrn, MCWF129 Series, 200 v. Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. MCWR06X1003FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. MCWR06X1003FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. MCWR06X1003FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. MCWR06X1003FTL - SMD Chip Resistor, 6003 [1608 Metric], 10 kohrn, MCWR Series, 50 v. MCWR06X1003FTL - MCWR06X1003FTL, 10 kohrn, MCWR06X1003FTL,	Farnell  Farnell  Farnell  Farnell  Farnell	2694448 2447230 2447226RL 2101833 2381866	RESC3216N  RESC1608N  RESC1608N  SOT23-3  PEC12R-4000F-S000C,1	R32, R33, R36, R37, R40 R2, R8, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41
1 18 2 2 2 2	470uF 25V  1k5 1/2W  10k  100k  NUP2105LT1G  PEC11R-4225F- S0024  6 Pin circular conn	MCVVT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 pf. 25. V/Y. Chip Series MCWF12975G1F1T SMD Chip Resistor, 1206 E216 Mering, 13. Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Mering]. 10. McWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Mering]. 10. McWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Mering]. 10. McWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Mering]. 10. McWR	Farnell  Farnell  Farnell  Farnell  Farnell	2694448  2447230  2447226RL  2101833  2381866	RESC3216N  RESC1608N  RESC1608N  SOT23-3  PEC12R-4000F-SXXXX_1  RPC1-12R8-6P(71)	R32, R33, R36, R37, R40 R2, R3, R5, R6, R6, R10, R11, R11, R11, R11, R12, R11, R14, R12, R12, R14, R12, R14, R14, R14, R14, R14, R14, R14, R44 R1, R4 R1, R4 ENC1
1 18 2 2 2 2	470uF 25V  185 1/2W  10k  100k  100k  NUP2105LT1G  PEC11R-4225F- 50024  6 Pin circular conn	MCVVT025M471G881 - SMD Aluminium Electrohytic Capacitor, Radial Can - SMD, 470 pf. 25 v. Vr. V-Chip Series MCWF12915G1F1T SMD Chip Resistor, 100 g210 Merinq, 15 v. Thick Film, 500 mW MCWR06X1002FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 10 kohm, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 10 kohm, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 10 kohm, MCWR Series, 50 v. Thick Film, 100 mW MCWR06X1003FTL - SMD Chip Resistor, 0603 [1608 Merinq]. 10 kohm, MCWR Series, 50 v. Thick Film, 100 mW MUP210STTG - TVS Diode, NUP21 Series, Bidirectional, 22 v. 40 v. SOT-23, 3 Pins PECTIR-4/225F-30024 - Rotary Encode, Mechanical, 24 v. 40 v. SOT-23, 3 Pins PECTIR-4/225F-30024 - Rotary Encode, Mechanical, 24 v. 40 v. SOT-23, 3 Pins PECTIR-4/225F-30024 - Rotary Encode, Mechanical, 24 v. 40 v. SOT-23, 3 Pins PECTIR-4/225F-30024 - Rotary Encode, Mechanical, 30 petents, Vertical, With Momentary bus Switch RPC-1-1/28R-6/P(71) - Circular Connector, RP series, Panel Mount Receptacle, 6 Contacts, Solder Pin STM327446RCT6 - ARM MCU. High Performance, STM32 Microcontrollers, ARM Cortex- M4, 32bit. TUP188(GR-TPL-SCT - Channel, SOP,	Farnell  Farnell  Farnell  Farnell  Farnell  Farnell	2694448  2447230  2447226RL  2101833  2381866  1077728	RESC3216N  RESC1608N  RESC1608N  SOT23-3  PEC12R-4000F-50000_1  RPC1-12RB-6P(71)  LOFP-64N	R32, R33, R36, R6, R37, R40 R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R15, R16, R15, R16, R17, R20, R26, R31, R35, R41  R1, R4  D2, D4  ENC1  U1

Our				Sunni	Supplie r Part	
tity	LogicalDesignator	Comment	Description SMD Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0005	er 1	1 6, 175916 6,	Footprint
			(2012 Metric), a 10%, X7R, MC Series,		9, 175916 6,	
			SMD Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0805 [2012 Metric], a 10%, X7R, MC Series, CL10A475KDBNMNC- SMD Multilayer Ceramic Capacitor,		175916 6, 175916 6,	
			LL10A475KDBNINNC - SMD Multilayer Ceramic Capacitor, 4.7 µF, 6.3 V, 0603		175916 6, 175916 6,	
		100nF,	Ceramic Capacitor, 4.7 pF, 6.3 V, 0603 [1608 Metric], a 10%, XSR, CL Series, MC000281044250CT - SMD Multilayer		175916 6. 175916 6.	
		100eF, 4u7F, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF, 100eF,	MC0008104K250CT- 3MD Multilayer Ceramic Capacitor, 0.1 pf; 25 V, 0005 [2012 Metric], a 10%, XTR, MC Series, MC00083904K250CT- SMD Multilayer Ceramic Capacitor, 0.1 pf; 25 V, 0005 [2012 Metric], a 10%, MC00083104K250CT- MC00083104K250CT- MC00083104K250CT- MMD Multilayer		175916 6, 175916 6, 175916	
		100nF, 100nF, 100nF, 100nF,	N/C08058104K250CT - SMD Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0805		6. 175916 A	
		100nF, 100nF, 100nF,	pari a Metric), a 10%, X7R, MC Series, MC000381048250CT - SMD Multilayer		175916 6. 175916 6.	
		100nF, 100nF, 100nF, 100nF, 100nF,	MC00008104C20CT - SMD Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0005 (2012 Metric), a 10%, X7R, MC Series, MC00008104C20CT - SMD Multilayer Ceramic Capacitor		175916 6. 175916 6.	
22	C1, C8, C12, C13, C14, C15, C16, C17, C18, C21, C22, C34, C35, C27, C38, C29, C31, C32, C34, C35, C36, C38	100nF, 100nF, 100nF, 100nF	MUUUDSB104K250CT - SMD Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0805	famel	175916 6, 175916 6,	CAPC1608N
			Ceramic Capacitor, 0.1 µF, 25 V, 0805 MCWR04X1002FTL- SMD Chip Resistor, 0603 [1608 Metric] 10 kohm, MCWR Series, 50 V, Thick Film, 100 mW		34**	
10	R2, R3, R5, R6, R9, R10, R11, R12, R13, R14, R15, R16, R17, R20, R26, R31, R35, R41	10k	MCU0603R103KCT -	Farnel	244723	RESC1608N
	C1, C2, C4, C3, C9, C10, C11, C23, C26, C30, C33, C40,	10=*	SMD Multilayer Ceramic Capacitor, 10000 pf, 50 V, 0603 [1608 Metric], a 10%, X7R, MCU Series	fer.	940618	CARCIAGAM
6	C42 C81, C84, C86, C87, C88, C813	10nF Open	Circuit Breaker CRGH0603F220R - SMD Chin Resistor	arnel		CR_0e03
			220 ohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200 mW.			
			CRGH0603F1K0 - SMD Chip Resistor, 1 kohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200 mW,			
			[1608 Metric], 200 mW, CRGH0603F220R - SMD Chip Resistor,			
			mW, CRGHOBOSII 220R - SMD Chip Resistor, 220 ohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric] 200 mW,			
			0003 [1608 Metric] 200 mW, CRGH0603F1K0 - SMD Chip Resistor, 1 kohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200			
			CRCHOMOTEZZOR -		233199 3, 231300	
			SMD Chip Resistor, 220 ohm, CRG Series, 50 V, Thick Film, 0x03 [1608 Metric], 200 mW, CRGH0803F1K0 -		233200 3, 233199 3, 233200	
		220R, 1k, 220R, 1k, 220R, 1k	0003 [1608 Metric] 200 mW, CRGH0603F1K0 - SMD Chip Resistor, 1 kohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200		233200 3, 233199 3, 233200	
٥	R7, R6, R21, R22, R27, R26	220R, 1k	MCWF12P1501FTL - SMD Chip Resistor, 1206 [3216 Metric]	Farnell	3	RESC1608N
	R32, R33, R36, R37, R40	1k5 1/2W	Series, 200 V, Thick Film, 500 mW	Farnell	269444 B	RESC3216N
	BIN_DN, BIN_OF, BIN_ON/OFF, BIN_UP	Button	Switch, Non Illuminated, 24 V, 50 mA, 225 gf, PC Pin,	Farn=1	261095 7	PB-4Xtenm
f			FSM Series BLM18PG471SN1D - Fernite Bead, 0603 (1608 Metric), 470 ohm, 1 A, BLM18P Series, 0.2 ohm, a 29%.	18		
4	12,13,14,15	BLM1BPG471 SN1D		farnell	151574 5	LL060312P
		ESCOPPAIL-	BSC070N10NS3GATM A1 - Power MOSFET, N Channel, 100 V, 90 A, 0.0063 ohm, TDSON, Surface		244***	
3	02; 03; 05; 06 082; 085; 0814	SIGATMA1 Closed	Mount Circuit Breaker	famel	244342 1	PG-TDSDN-B CB_0e03
_ 3	Q1, Q4, Q7	FMMT493AT A	Bipolar (BJT) Single Transistor, NPN, 60 V, 150 MHz, 500 mW, 1 A, 300 HFE	Farnell	206144 8	50123-3
			MCSR06X6BR0FTL - SMD Chip Resistor, 68 ohm, MCSR 06			
_3	R19, R25, R30	SER	Series, 75 V, Ceramic, 0603 [1608 Metric] 100 mW CL218105KEFNNNE - SMD Multilayer Ceramic Capacitor, 1 µF, 50 V, 0805 [2012	famel	207430	RESC1608N
_ 2	C43, C44	1uf 50V	Motrici, a 10%, X7R,	famel	301348 2	CAPC2012N
П			Metric], a 10%, X7R, CI, Series  0003M180500CT - SMD Multilayor  SMD Multilayor  Cerstric Capacitor,  0003 [1e08 Metric],  18 pf., 50 V, a 5%,  CGC / NPO  82755C12-G500 -  Zoner Single Diode,  12 V, 500 mW, 50D-  80 (MiniMELP), 5 %, 2  Plms, 175 °C,  NUP2105LT1G - TVS			
2	C6, C7	18p	18 pF, 50 V, a 5%, COG / NPO 8ZT55C12-G508 - Zener Single Direct	Farnell	249689 0	CAPC1608N
2	D1, D3	12V	12 V, 500 mW, 50D- 80 (MinIMELF), 5 %, 2 Plms, 175 °C	farnell	269002 B	500-80C
,	D2, D4	NUP2105LT1 G	Diode, NUP21 Series, Bidirectional, 22 V, 40 V, SDT-23, 3 Pins	Farnel	210183	50123-3
ſ		tkado	62409-1 - PCB Terminal, 6.35mm x 0.81mm, 0.25" x 0.032", Brass, 1.4 mm,			
2	Earth1; Earth2	Header	Tin MCCFB1206TFF/B - Fuse, Surface Mount, B A, 32 V,	farnel	285002	Blade header
2	rs, ra	BA .	Fast Acting, 1206 MCCFB1206TFF/1.5 - Fuse, Surface	farnell	165216	1206
2	13,14	1.5A Fuse	Fast Acting, 1206 Fast Acting, 1206 RPC1-1288-6P(71) - Circular Connector, RP Series, Panel Mount Receptacle, 6 Contacts, Solder Pin	farnell	٥	1206
2	P1, P2	6 Pin circular conn	RP Series, Panel Mount Receptacle, 6 Contacts, Solder Pin MCWR04X1003FTL- SMD Chip Resistor.	famel	107772	RPC1-12RB-6P(71)
	R1, 84	100k	MCWSSAN ROUST IL. SMID Chilp Resishor, 0603 [1600 Metric], 100 kohm, MCWR Series, 50 V, Block Fillen, 100 mW MCHVRS3JHS1000 - 5MD Chilp Resishor, High Voltage, 100 oths; HVRS Series, 200 V, Thick Fillen, 0603 [1608 Metric], 100 mW	Farn=1	244722 6RS	RESC1608N
П			MCHVR03/TEX1000 - SMD Chip Resistor, High Voltage, 100 phm, HVR Series. 200			
2	R23, R29	100R	BIB-XH-A (LF)(SN) -	famel	282569 6	RESC1608N
		51 7920 GLCD (128×64).	Connector, Vertical, 2.5 mm, 8 Contacts, Header, XH Series,			
2	ST7920 GLCD (128×64), ST7735 1.44inch	517920 GLCD (128×64), 517735 1,44inch	Through Hole, 1 Rows ACS711KLCTR-12AB-T - Current Sensor.	Farnell	151628 4	888-XH-A (LF)(SN)
2	U3, U6	ACS711KLCT R-12AB-T	Through Hole, 1 Rows ACS711HLCTR-12AB-T - Current Sensor, Overcurent Fault, 4 mA, 100 Mtz, 50HC, 8 Pms, 3 V, 55 V VOME2TTI - Photovolitalc MOSFET Driver, Integrated Fast Turn- Off, Solid-Stabe Perior 41th Get 24	Farnell	205742	SOIC-8
			Photovolitalc MOSFET Driver, Integrated Fast Turn- Off, Solid-State			
2	84, 67	VOM1271T	Off, Solid-State Relay 47µA Out, 24 µs Delay, SOP-4 µs Delay, SOP-4 MAX31855KASA+1 Temperature Sensor IC, Thermocouple, Digital, a 2°C, -200 °C, 1350 °C, NSOIC, B Dires	Farnell	239589 9	50P-4
_2	US, UB	MAKSTESSKA SA+T	IC, Thermocouple, Digital, a 2°C, -200 °C, 1350 °C, NSOIC, B Plns	famel	251562 2	SOIC-8
П			H11AA1SR2M - Optocoupler, Transhter Output, 1 Channel, Surface Mount DP, 6 Pins, 60 mA, 7.5 kV, 20 %			
2	uo, uto	H11AA15R2 M	Wount DIP, 6 Pins, 60 mA, 7.5 kV, 20 % RPT-20129GC - LED,	famel	232252 5	SMDP-6
,	+3V3DC	Green LED	SPT-2012SGC - LED, Low Power, Gesen, SMD, Jems s 1.25ms, 20 mA, 2.2 V, 568 rm CONNECTOR, 4 say; HEADER, THT, 3 SHAM, 10A, 250Ms: MCVVT025MHT1C8X, - SMD Alaminium Electrolytic Capacitor, Radial Can - SMD, 470 µF, 25 V, VT, V-Chip Series	Farnell	209923	LED_GRN
,	AC_IN1	HDR1X4	HEADER, THT, 3.96MM,10A,250Vac MCVVT025M471GB3L - SMD Aluminium	Farnell	949202	HDR1X4_3M96V
			Electrolytic Capacitor, Radial Can - SMD, 470 µF, 25 V, VT, V-Chip		261137	
-1	Car	470ulf 25V	series 1N4148W - Small Signal Diode, Single,	/arnell		10010.5
1	D5	1N4148W	1N414EW - Small Signal Diode, Single, 75 V, 150 mA, 1 V, 4 ns, 400 mA CONNECTOR, 2 way, HEADER, THT, 3 9646M, 10A, 250Vac		267746 4 949200	SOD-123F
H	DC_N	HDR1X2		r arnell	1	HDR1X2_3M96V
		PEC11R-	Rotary Encoder,     Mechanical,     Incremental, 24 PPR,     24 Detents, Vertical,     With Momentary     Dools Switch		238186	
H	ENCI	4225F-50024	Push Switch BLM18AG6015N1D - Femile Bead, 0603 [1608 Metric], 600 ohm, 500 mA, BLM18A Series, 0.38	r arnell	6	PEC12R-0000F-50000_1
,	u	BLM18A	B M210C221GM10 -	famel	151567 9	06031.
			Femite Bead, 0805 (2012 Metric), 220 ohm, 2 A, BLM21P Series, 0.045 ohm, a		151566	
H	LO.	/20R 2A	744235900 - Filter,	/arnell	1	LL0805/JP
١,	L7	300nH 2A	Line, Control Mode, JDD nH, WE- CNSW Series, 90 ohm, 2 A, 45mm x J2Mm s 2-8mm 1241050-3 - Board- To-Board Connector, J24 mm, 6 Contacts, Header, AMPMODU MOD B Series, Surface Mount, 2 Rows	Farnell	224986 5	1812_CM_WE
			10-Board Connector, 2.54 mm, 6 Contacts, Header, AMPMODU MOD Berles,		na-	
,	PROG	PROG	Surface Mount, 2 Rows CRGCQ1206/10M - SMD Chip Resistor.	Farnell	968956 7	B68_SMT
_ 1	R39	1084	Rows CRGC01206/10M - SMD Chip Resistor, 1206 (3216 Metric) 10 Mohm, CRGC0 Series, 200 V, Thick Film, 250 mW	Farnell	286197 4	RESC3216N
-	SPD	Sleep_Det	2 header, 2.54mm STM32F446RCT6 - ARM MCU, High Performance, STM32	Farnell	124814	HDR1X2_2.54mm
			Performance, STM32 Family STM32F4 Series Microcontrollers, ARM Cortes-M4, 32bit			
-	uı	STM32F446R CT6		farnell	248830 9	LOFP-64N
١,	נווו	TLP1855E	Optocoupler, 1 Channel, 50P, 4 Plm, 50 mA, 3.75 kV, 100 % 24LC256-E/SN -	Farnell	301409 7	SOP-4
1	uz	24LC256- E/SN	EEPROM, 256 Kbit, 32K x 8bit, Serial I2C (2-Wire), 400 kHz, SOIC, 8 Pins	famel	157957	SOIC-8
	xı	8 MHz	CRISTAL, BM, 1897 CL, 6K3-6MM SMT	Farnell	161180	25MX-35M68

## **Design Rules Verification Report**

Filename : C:\Users\Aurimas\OneDrive\Projects\JBCproject\JBCT245\_1v1\T245\_1v1.PcbD

Warnings 4 Rule Violations 500

Warnings	
Zero hole size multi-layer pad(s) detected	2
Multilayer Pads with 0 size Hole found	2
Total	4

Rule Violations	
Clearance Constraint (Gap=0.3mm) (All),(All)	137
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ( (All) )	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.1mm) (Max=10mm) (Preferred=0.3mm) (All)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	88
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	270
Silk to Silk (Clearance=0.254mm) (AII),(AII)	5
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=50mm) (Prefered=12.7mm) (All)	0
Total	500

# Zero hole size multi-layer pad(s) detected Pad Earth1-1(116.557mm,13.14mm) on Multi-Layer on Net GND Pad Earth2-1(116.565mm,6.63mm) on Multi-Layer on Net GND

Multilayer Pads with 0 size Hole found
Pad Earth1-1(116.557mm,13.14mm) on Multi-Layer
Pad Earth2-1(116.565mm,6.63mm) on Multi-Layer

```
Clearance Constraint (Gap=0.3mm) (All),(All)
Clearance Constraint: (0.25mm < 0.3mm) Between Track (61.56mm,95.78mm)(61.56mm,106.75mm) on Top Layer And Pad ST7920 GLCD
Clearance Constraint: (0.25mm < 0.3mm) Between Track (61.56mm,95.78mm)(61.56mm,106.75mm) on Top Layer And Pad ST7920 GLCD
Clearance Constraint: (0.25mm < 0.3mm) Between Track (64.06mm, 107.04mm)(64.06mm, 109.25mm) on Top Layer And Pad ST7735
Clearance Constraint: (0.25mm < 0.3mm) Between Track (64.06mm,107.04mm)(64.06mm,109.25mm) on Top Layer And Pad ST7735
Clearance Constraint: (0.2mm < 0.3mm) Between Track (82.59mm,19.38mm)(85.83mm,19.38mm) on Top Layer And Pad D2-3(83.48mm,18.43mm) on Top
Clearance Constraint: (0.2mm < 0.3mm) Between Track (21.455mm,18.9mm)(25.7mm,18.9mm) on Top Layer And Pad D4-3(23.35mm,17.95mm) on Top
Clearance Constraint: (0.2mm < 0.3mm) Between Track (21.395mm,17mm)(25.7mm,17mm) on Top Layer And Pad D4-3(23.35mm,17.95mm) on Top Layer
Clearance Constraint: (0.183mm < 0.3mm) Between Via (24.76mm,17.95mm) from Top Layer to Bottom Layer And Pad D4-2(25.7mm,18.9mm) on Top
Clearance Constraint: (0.183mm < 0.3mm) Between Via (24.76mm, 17.95mm) from Top Layer to Bottom Layer And Pad D4-1(25.7mm, 17mm) on Top Layer
Clearance Constraint: (0.292mm < 0.3mm) Between Region (0 hole(s)) Bottom Layer And Pad CB8-2(28.58mm, 16.607mm) on Bottom Layer
Clearance Constraint: (0.24mm < 0.3mm) Between Track (27.105mm,18.545mm)(30.51mm,18.545mm) on Bottom Layer And Pac
Clearance Constraint: (0.21mm < 0.3mm) Between Track (27.105mm,18.545mm)(30.51mm,18.545mm) on Bottom Layer And Pad
Clearance Constraint: (0.28mm < 0.3mm) Between Pad C11-1(63.67mm,39.55mm) on Bottom Layer And Pad C9-1(63.68mm,40.83mm) on Bottom Layer
Clearance Constraint: (0.24mm < 0.3mm) Between Track (60.82mm, 39.48mm)(60.82mm, 40.29mm) on Bottom Layer And Pad R13-2(60.82mm, 41.13mm)
Clearance Constraint: (0.24mm < 0.3mm) Between Track (58.79mm,40.29mm)(60.82mm,40.29mm) on Bottom Layer And Pad R13-2(60.82mm,41.13mm)
Clearance Constraint: (0.24mm < 0.3mm) Between Track (60.82mm,40.29mm)(62.93mm,40.29mm) on Bottom Layer And Pad R13-2(60.82mm,41.13mm)
Clearance Constraint: (0.295mm < 0.3mm) Between Track (61.6mm, 38.56mm)(62.25mm, 39.21mm) on Bottom Layer And Pad R13-1(60.82mm, 39.43mm)
Clearance Constraint: (0.22mm < 0.3mm) Between Track (59.42mm, 38.56mm) (61.6mm, 38.56mm) on Bottom Layer And Pad R13-1(60.82mm, 39.43mm) or
Clearance Constraint: (0.26mm < 0.3mm) Between Track (62.93mm,40.29mm)(63.47mm,40.83mm) on Bottom Layer And Pad R16-2(62.25mm,41.14mm)
Clearance Constraint: (0.25mm < 0.3mm) Between Track (60.82mm,40.29mm)(62.93mm,40.29mm) on Bottom Layer And Pad R16-2(62.25mm,41.14mm)
Clearance Constraint: (0.289mm < 0.3mm) Between Track (62.93mm,40.29mm)(63.47mm,40.83mm) on Bottom Layer And Pad R16-1(62.25mm,39.44mm)
Clearance Constraint: (0.25mm < 0.3mm) Between Track (60.82mm.40.29mm)(62.93mm.40.29mm) on Bottom Layer And Pad R16-1(62.25mm.39.44mm)
Clearance Constraint: (0.274mm < 0.3mm) Between Track (38.837mm,51.04mm)(39.937mm,52.14mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.787mm,49.97mm)(40.787mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (42.287mm,65.308mm)(42.287mm,69.097mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.767mm,61.57mm)(32.517mm,62.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.517mm,62.32mm)(33.799mm,62.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.248mm < 0.3mm) Between Track (30.93mm,67.6mm)(33.32mm,65.21mm) on Bottom Layer And Pad C15-2(32.197mm,64.77mm)
Clearance Constraint: (0.241mm < 0.3mm) Between Track (37.787mm,52.69mm)(38.337mm,52.14mm) on Bottom Layer And Pad
Clearance Constraint: (0.241mm < 0.3mm) Between Track (37.787mm,52.69mm)(37.787mm,53.832mm) on Bottom Layer And Paci
Clearance Constraint: (0.28mm < 0.3mm) Between Pad R30-1(35.51mm,90.84mm) on Bottom Layer And Pad C38-1(35.36mm,92.12mm) on Bottom Layer
Clearance Constraint: (0.292mm < 0.3mm) Between Region (0 hole(s)) Bottom Layer And Pad CB7-2(35.927mm,69.45mm) on Bottom Layer
Clearance Constraint: (0.292mm < 0.3mm) Between Region (0 hole(s)) Bottom Layer And Pad CB5-2(34.213mm,68.02mm) on Bottom Layer
Clearance Constraint: (0.263mm < 0.3mm) Between Via (35.48mm,66.75mm) from Top Layer to Bottom Layer And Pad CB5-1(35.927mm,68.02mm) or
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-2(42.787mm,53.832mm) on Bottom Layer And Pad U1-1(43.287mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (43.287mm,52.25mm)(43.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-5(41.287mm,53.832mm) on Bottom Layer And Pad U1-4(41.787mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (41.287mm.50.05mm)(41.287mm.53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-6(40.787mm,53.832mm) on Bottom Layer And Pad U1-5(41.287mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.787mm,49.97mm)(40.787mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-7(40.287mm,53.832mm) on Bottom Layer And Pad U1-6(40.787mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,53.832mm)(40.287mm,55.987mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,52.44mm)(40.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (41,287mm,50.05mm)(41,287mm,53,272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (39.787mm,53.832mm)(39.787mm,56.127mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.787mm,49.97mm)(40.787mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-8(39.787mm,53.832mm) on Bottom Layer And Pad U1-7(40.287mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-9(39.287mm,53.832mm) on Bottom Layer And Pad U1-8(39.787mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (39.287mm,53.832mm)(39.287mm,56.257mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,53.832mm)(40.287mm,55.987mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,52.44mm)(40.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-10(38.787mm,53.832mm) on Bottom Layer And Pad U1-9(39.287mm,53.832mm) on Bottom
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Clearance Constraint (Gap=0.3mm) (All),(All)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.787mm,53.832mm)(38.787mm,56.417mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (39.787mm,53.832mm)(39.787mm,56.127mm) on Bottom Layer And Pac
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-11(38.287mm,53.832mm) on Bottom Layer And Pad U1-10(38.787mm,53.832mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.287mm,53.832mm)(38.287mm,56.557mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (39.287mm,53.832mm)(39.287mm,56.257mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,52.69mm)(37.787mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,53.832mm)(37.787mm,55.941mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.787mm,53.832mm)(38.787mm,56.417mm) on Bottom Layer And Paci
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-12(37.787mm,53.832mm) on Bottom Layer And Pad U1-11(38.287mm,53.832mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-13(37.287mm,53.832mm) on Bottom Layer And Pad U1-12(37.787mm,53.832mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.287mm,52.312mm)(37.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.287mm,53.832mm)(38.287mm,56.557mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-14(36.787mm,53.832mm) on Bottom Layer And Pad U1-13(37.287mm,53.832mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.787mm,53.832mm)(36.787mm,55.5mm) on Bottom Layer And Pac
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,52.69mm)(37.787mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm.53.832mm)(37.787mm.55.941mm) on Bottom Layer And Page
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-15(36.287mm,53.832mm) on Bottom Layer And Pad U1-14(36.787mm,53.832mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.287mm,53.832mm)(36.287mm,54.633mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.287mm,52.312mm)(37.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.244mm < 0.3mm) Between Track (35.68mm,55.24mm)(36.287mm,54.633mm) on Bottom Layer And Paci
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.787mm,53.832mm)(36.787mm,55.5mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (35.775mm.53.82mm)(35.787mm.53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-16(35.787mm,53.832mm) on Bottom Layer And Pad U1-15(36.287mm,53.832mm) on Bottom
Clearance Constraint: (0.212mm < 0.3mm) Between Track (34.9mm,53.82mm)(35.775mm,53.82mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.287mm,53.832mm)(36.287mm,54.633mm) on Bottom Layer And Pad
Clearance Constraint: (0.204mm < 0.3mm) Between Track (35.68mm,55.24mm)(36.287mm,54.633mm) on Bottom Layer And Pad
Clearance Constraint: (0.283mm < 0.3mm) Between Track (32.557mm,55.99mm)(32.887mm,56.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-18(33.799mm,56.32mm) on Bottom Layer And Pad U1-17(33.799mm,55.82mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.887mm,56.32mm)(33.799mm,56.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-19(33.79mm,56.82mm) on Bottom Layer And Pad U1-18(33.799mm,56.32mm) on Bottom Layer
Clearance Constraint: (0.23mm < 0.3mm) Between Track (33.51mm,53.64mm)(33.51mm,55.79mm) on Bottom Layer And Pad U1-18(33.799mm,56.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.117mm,56.82mm)(33.799mm,56.82mm) on Bottom Layer And Pad
Clearance Constraint: (0.296mm < 0.3mm) Between Track (32.557mm,55.99mm)(32.887mm,56.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-20(33.799mm,57.32mm) on Bottom Layer And Pad U1-19(33.799mm,56.82mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (33.799mm,57.32mm)(35.88mm,57.32mm) on Bottom Layer And Pad U1-19(33.799mm,56.82mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.887mm,56.32mm)(33.799mm,56.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-21(33.79mm,57.82mm) on Bottom Layer And Pad U1-20(33.799mm,57.32mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.117mm.56.82mm)(33.799mm.56.82mm) on Bottom Layer And Page
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.07mm,57.82mm)(33.799mm,57.82mm) on Bottom Layer And Pad U1-20(33.799mm,57.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (33.799mm,57.32mm)(35.88mm,57.32mm) on Bottom Layer And Pad U1-21(33.799mm,57.82mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-22(33.799mm,58.32mm) on Bottom Layer And Pad U1-21(33.799mm,57.82mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.93mm,58.32mm)(33.799mm,58.32mm) on Bottom Layer And Pad U1-21(33.799mm,57.82mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-23(33.799mm,58.82mm) on Bottom Layer And Pad U1-22(33.799mm,58.32mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (33,799mm.58.82mm)(36,31mm.58.82mm) on Bottom Layer And Pad U1-22(33,799mm.58.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.07mm,57.82mm)(33.799mm,57.82mm) on Bottom Layer And Pad U1-22(33.799mm,58.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-24(33.79mm,59.32mm) on Bottom Layer And Pad U1-23(33.799mm,58.82mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (33.799mm,59.32mm)(35.44mm,59.32mm) on Bottom Layer And Pad U1-23(33.799mm,58.82mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.93mm,58.32mm)(33.799mm,58.32mm) on Bottom Layer And Pad U1-23(33.799mm,58.82mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (33.799mm,58.82mm)(36.31mm,58.82mm) on Bottom Layer And Pad U1-24(33.799mm,59.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-25(33.799mm,59.82mm) on Bottom Layer And Pad U1-24(33.799mm,59.32mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.4mm,59.82mm)(33.799mm,59.82mm) on Bottom Layer And Pad U1-24(33.799mm,59.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (33.799mm,59.32mm)(35.44mm,59.32mm) on Bottom Layer And Pad U1-25(33.799mm,59.82mm)
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## Clearance Constraint (Gap=0.3mm) (All),(All) Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-26(33.799mm,60.32mm) on Bottom Layer And Pad U1-25(33.799mm,59.82mm) on Bottom Layer Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.4mm,59.82mm)(33.799mm,59.82mm) on Bottom Layer And Pad U1-26(33.799mm,60.32mm) Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.88mm,61.82mm) (33.799mm,61.82mm) on Bottom Layer And Pad U1-28(33.799mm,61.32mm) Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-29(33.799mm,61.82mm) on Bottom Layer And Pad U1-28(33.799mm,61.32mm) on Bottom Layer Clearance Constraint: (0.288mm < 0.3mm) Between Track (31.64mm,60.58mm)(32.88mm,61.82mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-30(33.799mm,62.32mm) on Bottom Layer And Pad U1-29(33.799mm,61.82mm) on Bottom Layer Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.517mm,62.32mm)(33.799mm,62.32mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.88mm,61.82mm)(33.799mm,61.82mm) on Bottom Layer And Pad U1-30(33.799mm,62.32mm) Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-31(33.799mm,62.82mm) on Bottom Layer And Pad U1-30(33.799mm,62.32mm) on Bottom Layer Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.327mm,62.82mm)(33.799mm,62.82mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-32(33.799mm,63.32mm) on Bottom Layer And Pad U1-31(33.799mm,62.82mm) on Bottom Layer Clearance Constraint: (0.23mm < 0.3mm) Between Track (33.799mm,63.5mm)(33.799mm,64.101mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.517mm,62.32mm)(33.799mm,62.32mm) on Bottom Layer And Pac Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.327mm,62.82mm)(33.799mm,62.82mm) on Bottom Layer And Pac Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.287mm,65.308mm)(36.287mm,66.583mm) on Bottom Layer And Paci Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-34(36.287mm.65.308mm) on Bottom Layer And Pad U1-33(35.787mm.65.308mm) on Bottom Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.787mm,65.308mm)(36.787mm,67.523mm) on Bottom Layer And Paci Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-35(36.787mm,65.308mm) on Bottom Layer And Pad U1-34(36.287mm,65.308mm) on Bottom Clearance Constraint: (0.2mm < 0.3mm) Between Track (35.432mm,65.308mm)(35.787mm,65.308mm) on Bottom Layer And Paci Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.287mm,65.308mm)(37.287mm,68.793mm) on Bottom Layer And Paci Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.287mm,65.308mm)(36.287mm,66.583mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-36(37.287mm.65.308mm) on Bottom Layer And Pad U1-35(36.787mm.65.308mm) on Bottom Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.787mm,65.308mm)(36.787mm,67.523mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,64.103mm)(37.787mm,65.308mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-37(37.787mm,65.308mm) on Bottom Layer And Pad U1-36(37.287mm,65.308mm) on Bottom Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.287mm,64.233mm)(38.287mm,65.308mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.287mm,65.308mm)(37.287mm,68.793mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-38(38.287mm,65.308mm) on Bottom Layer And Pad U1-37(37.787mm,65.308mm) on Bottom Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.787mm,64.413mm)(38.787mm,65.308mm) on Bottom Layer And Pad Clearance Constraint: (0.287mm < 0.3mm) Between Track (38.787mm,64.413mm)(39.16mm,64.04mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-39(38.787mm,65.308mm) on Bottom Layer And Pad U1-38(38.287mm,65.308mm) on Bottom Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,64.103mm)(37.787mm,65.308mm) on Bottom Layer And Pad Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.287mm,64.233mm)(38.287mm,65.308mm) on Bottom Layer And Pad

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Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad D2-2(85.83mm,19.38mm) on Top Layer And Pad C24-1(85.85mm,20.7mm)
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad D2-1(85.83mm,17.48mm) on Top Layer And Pad C27-2(85.61mm,16.16mm)
Minimum Solder Mask Sliver Constraint: (0.152mm < 0.254mm) Between Pad Q4-2(82.6mm,25.29mm) on Top Layer And Pad R22-1(82.42mm,23.96mm)
Minimum Solder Mask Sliver Constraint: (0.152mm < 0.254mm) Between Pad Q4-1(80.7mm,25.29mm) on Top Layer And Pad R22-2(80.72mm,23.96mm)
Minimum Solder Mask Sliver Constraint: (0.237mm < 0.254mm) Between Pad R19-1(81.92mm, 30.24mm) on Top Layer And Pad U4-1(83.51mm, 30.19mm)
Minimum Solder Wask Sliver Constraint: (0.237mm < 0.254mm) Between Pad R21-2(79.31mm, 25.23mm) on Top Layer And Pad Q4-1(80.7mm, 25.29mm)
Minimum Solder Wask Sliver Constraint: (0.252mm < 0.254mm) Between Pad D2-2(85.83mm,19.38mm) on Top Layer And Pad C26-1(87.26mm,19.24mm)
Minimum Solder Wask Sliver Constraint: (0.252mm < 0.254mm) Between Pad D2-1(85.83mm,17.48mm) on Top Layer And Pad C26-1(87.26mm,17.64mm)
Minimum Solder Wask Sliver Constraint: (0.23241111) Between Pad C32-2(19.71mm,21.02mm) on Top Layer And Pad C20-2(07.2011111,177.0411111)
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad C32-1(21.31mm,21.02mm) on Top Layer And Pad  Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad C32-1(21.31mm,21.02mm) on Top Layer And Pad D3 1(32.55mm, 20.37mm)
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad C28-2(31.79mm,29.32mm) on Top Layer And Pad D3-1(33.55mm,30.3mm)
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad C28-1(31.79mm,27.72mm) on Top Layer And Pad D3-2(33.55mm,26.66mm)
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad U7-4(30.14mm,29.265mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad Q7-1(20.59mm,24.54mm) on Top Layer And Pad R27-2(19.19mm,24.45mm)
Minimum Solder Mask Sliver Constraint: (0.082mm < 0.254mm) Between Pad Q7-2(22.49mm,24.54mm) on Top Layer And Pad R28-1(22.35mm,23.28mm)
Minimum Solder Mask Sliver Constraint: (0.082mm < 0.254mm) Between Pad Q7-1(20.59mm,24.54mm) on Top Layer And Pad R28-2(20.65mm,23.28mm)
Minimum Solder Mask Sliver Constraint: (0.127mm < 0.254mm) Between Pad C31-1(25.69mm,20.18mm) on Top Layer And Pad D4-2(25.7mm,18.9mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad C34-2(25.69mm, 15.75mm) on Top Layer And Pad D4-1(25.7mm, 17mm) or
Minimum Solder Mask Sliver Constraint: (0.013mm < 0.254mm) Between Pad R26-2(28.57mm,17.68mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.089mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB8-2(28.58mm, 16.607mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB8-1(28.58mm, 14.893mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB8-1(28.58mm,14.893mm) or
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad R31-1(81.33mm,49.55mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad R35-1(80.01mm,58.04mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad R35-2(80.01mm,56.34mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.057mm < 0.254mm) Between Pad D5-1(45.07mm, 37.54mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.137mm < 0.254mm) Between Pad U11-3(34.9mm, 40.14mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad C 44-1(31.74mm, 40.02mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad C 44-2(31.74mm,38.32mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R17-2(67.69mm,57.96mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R17-1(67.69mm,56.26mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.077mm < 0.254mm) Between Pad C11-1(63.67mm,39.55mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad R16-2(62.25mm,41.14mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.077mm < 0.254mm) Between Pad C11-2(65.27mm,39.55mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R11-2(59.41mm,41.14mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R11-1(59.41mm,39.44mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad R11-2(59.41mm,41.14mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad R16-2(62.25mm,41.14mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad R11-1(59.41mm,39.44mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad R16-1(62.25mm,39.44mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad C11-1(63.67mm, 39.55mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.195mm < 0.254mm) Between Pad L1-1(37.059mm,52.13mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-11(38.287mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-10(38.787mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R1-1(37.84mm,50.69mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-12(37.787mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.254mm < 0.254mm) Between Pad U1-9(39.287mm, 53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-7(40.287mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-8(39.787mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.249mm < 0.254mm) Between Pad U1-48(43.287mm,65.308mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.111mm < 0.254mm) Between Pad U1-47(42.787mm,65.308mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.188mm < 0.254mm) Between Pad U1-46(42.287mm,65.308mm) on Bottom Layer And Pac

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Minimum Solder Mask Sliver (C	Sap=0.254mm) (AII),(AII)
Minimum Solder Mask Sliver Constra	int: (0.199mm < 0.254mm) Between Pad CB4-1(30.787mm,63.227mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constra	int: (0.161mm < 0.254mm) Between Pad U1-31(33.799mm,62.82mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constra	int: (0.23mm < 0.254mm) Between Pad U1-30(33.799mm,62.32mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.199mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad C15-1(32.197mm,63.17mm) on Bottom
Minimum Solder Mask Sliver Constra	int: (0.199mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad C15-1(32.197mm,63.17mm) on Bottom
Minimum Solder Mask Sliver Constra	int: (0.04mm < 0.254mm) Between Pad C18-2(34.537mm,52.12mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.244mm < 0.254mm) Between Pad X1-3(39.837mm,49.79mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.097mm < 0.254mm) Between Pad R3-2(102.47mm,69.93mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.097mm < 0.254mm) Between Pad R3-1(100.77mm,69.93mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.097mm < 0.254mm) Between Pad R2-2(104.85mm,87.83mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.097mm < 0.254mm) Between Pad R2-1(106.55mm,87.83mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.197mm < 0.254mm) Between Pad Q1-1(81.2mm,100.29mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.227mm < 0.254mm) Between Pad L6-1(33.66mm,95.18mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.157mm < 0.254mm) Between Pad C38-2(33.76mm,92.12mm) on Bottom Layer And Pad
	int: (0.077mm < 0.254mm) Between Pad R30-1(35.51mm,90.84mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.077mm < 0.254mm) Between Pad R30-2(33.81mm,90.84mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.197mm < 0.254mm) Between Pad C 4-1(21.34mm,89.04mm) on Bottom Layer And Pad R5-2(21.4mm,87.64mm)
Minimum Solder Mask Sliver Constra	int: (0.197mm < 0.254mm) Between Pad C 4-2(19.74mm,89.04mm) on Bottom Layer And Pad R5-1(19.7mm,87.64mm)
Minimum Solder Mask Sliver Constra	int: (0.067mm < 0.254mm) Between Pad R6-2(25.22mm,69.82mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.067mm < 0.254mm) Between Pad R6-1(23.52mm,69.82mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.211mm < 0.254mm) Between Pad CB5-1(35.927mm,68.02mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constra	int: (0.089mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-2(35.927mm,69.45mm) or
Minimum Solder Mask Sliver Constra	int: (0.217mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-2(35.927mm,69.45mm) or
Minimum Solder Mask Sliver Constra	int: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-2(35.927mm,69.45mm) or
Minimum Solder Mask Sliver Constra	int: (0.211mm < 0.254mm) Between Pad CB5-2(34.213mm,68.02mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constra	int: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-1(34.213mm,69.45mm) or
	int: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-1(34.213mm,69.45mm) or
Minimum Solder Mask Sliver Constra	int: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-1(34.213mm,69.45mm) or
Minimum Solder Mask Sliver Constra	int: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-2(34.213mm,68.02mm) or
	int: (0.217mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-2(34.213mm,68.02mm) or
	int: (0.089mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-2(34.213mm,68.02mm) or
Minimum Solder Mask Sliver Constra	int: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-1(35.927mm,68.02mm) or
	int: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-1(35.927mm,68.02mm) or
	int: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-1(35.927mm,68.02mm) or
Minimum Solder Mask Sliver Constra	int: (0.151mm < 0.254mm) Between Pad C17-2(43.63mm,52.24mm) on Bottom Layer And Pad
Minimum Solder Mask Sliver Constra	int: (0.218mm < 0.254mm) Between Pad C 17-2(43.63mm,52.24mm) on Bottom Layer And Pad

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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (80.75mm,26.04mm) on Top Overlay And Pad Q4-1(80.7mm,25.29mm) or
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (85.08mm, 17.53mm) on Top Overlay And Pad D2-1(85.83mm, 17.48mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (92.995mm, 9.625mm) on Top Overlay And Pad L3-1(87.25mm, 14.835mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (92.995mm, 9.625mm) on Top Overlay And Pad L2-1(88.61mm, 16.285mm)
Silk To Solder Mask Clearance Constraint: (0.121mm < 0.254mm) Between Arc (92.995mm, 9.625mm) on Top Overlay And Pad L2-2(88.61mm, 14.835mm)
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (20.64mm,25.29mm) on Top Overlay And Pad Q7-1(20.59mm,24.54mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (32.995mm, 9.625mm) on Top Overlay And Pad L4-1(28.61mm, 15.815mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (32.995mm, 9.625mm) on Top Overlay And Pad L5-1(27.17mm, 14.365mm)
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (24.95mm,17.05mm) on Top Overlay And Pad D4-1(25.7mm,17mm) or
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Arc (35.86mm,102.77mm) on Bottom Overlay And Pad
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (35.86mm,102.77mm) on Bottom Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (80.45mm,100.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (48.097mm, 70.045mm) on Bottom Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Arc (110.689mm,30.718mm) on Bottom Overlay And Pad
Silk To Solder Mask Clearance Constraint: (c. mm < c.254mm) Between Track (117.05mm,41.58mm)(117.05mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (119.59mm,41.58mm)(119.59mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (117.05mm,41.58mm)(117.05mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (119.59mm,41.58mm)(119.59mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.162mm < 0.254mm) Between Text "L2" (88.4mm, 12.26mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (69.03mm,44.26mm)(69.03mm,48.36mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (69.03mm,53.56mm)(69.03mm,57.66mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (56.63mm,44.26mm)(56.63mm,48.36mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (56.63mm,53.56mm)(56.63mm,57.66mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.22mm < 0.254mm) Between Text "C25" (80.84mm,22.24mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.22mm < 0.254mm) Between Text "C25" (80.84mm,22.24mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.875mm,15.56mm)(87.875mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.985mm,15.56mm)(87.985mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (89.235mm,15.56mm)(89.235mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.875mm,15.185mm)(87.875mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.985mm,15.185mm)(87.985mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (89.235mm,15.185mm)(89.235mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (86.625mm,15.185mm)(86.625mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.875mm,15.185mm)(87.875mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.985mm,15.185mm)(87.985mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (86.625mm, 15.56mm)(86.625mm, 15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.875mm,15.56mm)(87.875mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.985mm, 15.56mm)(87.985mm, 15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (108.471mm,85.55mm)(108.471mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (102.832mm,85.55mm)(108.471mm,85.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (108.471mm,85.55mm)(108.471mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (102.832mm,91.55mm)(108.471mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (27.231mm,67.58mm)(27.231mm,73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (21.592mm, 67.58mm)(27.231mm, 67.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (27.231mm, 67.58mm)(27.231mm, 73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (21.592mm, 73.58mm)(27.231mm, 73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (23.181mm, 85.55mm)(23.181mm, 91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (17.542mm, 85.55mm)(23.181mm, 85.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (23.181mm, 85.55mm)(23.181mm, 91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (17.542mm,91.55mm)(23.181mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (104.431mm,67.58mm)(104.431mm,73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (98.792mm,67.58mm)(104.431mm,67.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (104.431mm,67.58mm)(104.431mm,73.58mm) on Top Overlay And Pac
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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (98.792mm, 73.58mm)(104.431mm, 73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (81.37mm,24.36mm)(81.77mm,24.36mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (81.37mm,23.56mm) (81.77mm,23.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.17mm < 0.254mm) Between Text "C 25" (80.84mm,22.24mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (81.37mm,24.36mm)(81.77mm,24.36mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (81.37mm,23.56mm)(81.77mm,23.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.17mm < 0.254mm) Between Text "C 25" (80.84mm, 22.24mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (93.24mm, 27.15mm)(93.24mm, 30.59mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (94.8mm,27.15mm)(94.8mm,30.59mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (93.24mm, 30.59mm) (94.8mm, 30.59mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision C. 0.254mm) Between Track (93.24mm, 30.19mm) (94.8mm, 30.19mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Orlinin < 0.254mm) Between Track (93.24mm, 27.15mm)(93.24mm, 30.59mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (94.8mm,27.15mm)(94.8mm,30.59mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (93.24mm, 27.15mm)(94.8mm, 27.15mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.225mm < 0.254mm) Between Track (89.035mm,26.765mm)(89.035mm,31.065mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.225mm < 0.254mm) Between Track (89.035mm,26.765mm)(89.035mm,31.065mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.153mm < 0.254mm) Between Text "Q4" (81.24mm,28.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.103mm < 0.254mm) Between Track (82.455mm,27.065mm)(82.95mm,27.065mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.103mm < 0.254mm) Between Track (82.95mm,26.165mm)(82.95mm,27.065mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.87mm,29.84mm)(81.27mm,29.84mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.87mm,30.64mm) (81.27mm,30.64mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.87mm,29.84mm)(81.27mm,29.84mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.87mm,30.64mm) (81.27mm,30.64mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.14mm < 0.254mm) Between Text "Q4" (81.24mm,28.55mm) on Top Overlay And Pad
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Text "R22" (80.061mm,25.364mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Text "R22" (80.061mm,25.364mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Text "U4" (82.09mm,26.816mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (78.91mm,25.88mm)(78.91mm,26.28mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (79.71mm,25.88mm)(79.71mm,26.28mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.227mm < 0.254mm) Between Text "R22" (80.061mm,25.364mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (78.91mm,25.88mm)(78.91mm,26.28mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (79.71mm,25.88mm)(79.71mm,26.28mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.197mm < 0.254mm) Between Text "R21" (79.8mm,22.2mm) on Top Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.201mm < 0.254mm) Between Text "R22" (80.061mm,25.364mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (80.615mm,15.82mm)(80.615mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Track (79.008mm, 15.82mm)(80.615mm, 15.82mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (80.615mm,15.82mm)(80.615mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (80.615mm,15.82mm)(80.615mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (80.615mm,15.82mm)(80.615mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (76.74mm,15.82mm)(76.74mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.23mm < 0.254mm) Between Track (76.74mm, 15.82mm)(78.373mm, 15.82mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (76.74mm,15.82mm)(76.74mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (76.74mm,15.82mm)(76.74mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (76.74mm,15.82mm)(76.74mm,20.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (82.9mm, 19.73mm) (103.1mm, 19.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.005mm < 0.254mm) Between Track (82.9mm,-0.47mm)(82.9mm,19.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (82.9mm, 19.73mm) (103.1mm, 19.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (20.235mm,15.49mm)(20.235mm,20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.15mm < 0.254mm) Between Track (18.628mm, 15.49mm)(20.235mm, 15.49mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (20.235mm,15.49mm)(20.235mm,20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (20.235mm,15.49mm)(20.235mm,20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (20.235mm,15.49mm)(20.235mm,20.4mm) on Top Overlay And Pac

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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (16.36mm, 15.49mm)(16.36mm, 20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.23mm < 0.254mm) Between Track (16.36mm,15.49mm)(17.993mm,15.49mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (16.36mm,15.49mm)(16.36mm,20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (16.36mm, 15.49mm)(16.36mm, 20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (16.36mm, 15.49mm)(16.36mm, 20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (32.77mm, 26.76mm)(32.77mm, 30.2mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (34.33mm, 26.76mm)(34.33mm, 30.2mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (32.77mm, 30.2mm)(34.33mm, 30.2mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0mm < 0.254mm) Between Track (32.77mm,29.8mm)(34.33mm,29.8mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (32.77mm,26.76mm)(32.77mm,30.2mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (34.33mm, 26.76mm)(34.33mm, 30.2mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (32.77mm, 26.76mm)(34.33mm, 26.76mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (collision < 0.254mm) Between Track (29.165mm,25.84mm)(29.165mm,30.14mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.225mm < 0.254mm) Between Track (27.165mm,25.84mm)(29.165mm,30.14mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.223/mm < 0.254/mm) Between Track (22.345mm,26.315mm)(22.84mm,26.315mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.13mm < 0.254mm) Between Track (22.84mm,25.415mm)(22.84mm,26.315mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.13mm < 0.254mm) Between Track (20.87mm,28.85mm) (21.27mm,28.85mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.87mm,29.65mm) (21.27mm,29.65mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.87mm,28.85mm) (21.27mm,28.85mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.87mm,29.65mm)(21.27mm,29.65mm) on Top Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (18.79mm,25.1mm)(18.79mm,25.5mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (19.59mm,25.1mm)(19.59mm,25.5mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (18.79mm,25.1mm)(18.79mm,25.5mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (19.59mm,25.1mm)(19.59mm,25.5mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (21.3mm,22.88mm)(21.7mm,22.88mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (21.3mm,23.68mm)(21.7mm,23.68mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (21.3mm,22.88mm)(21.7mm,22.88mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (21.3mm,23.68mm)(21.7mm,23.68mm) on Top Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.073mm < 0.254mm) Between Track (20.235mm,15.49mm)(20.235mm,20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.07smm < 0.254mm) Between Track (20.235mm, 13.49mm)(20.235mm, 20.4mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.07mm < 0.254mm) Between Text "R28" (23.14mm,22.87mm) on Top Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.254mm) Between Track (26.545mm,14.715mm)(26.545mm,15.09mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (20.345mm, 14.715mm)(27.795mm, 15.09mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (27.795mm, 15.09mm)(26.545mm, 15.465mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (27.795mm,15.09mm)(27.795mm,15.465mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (29.235mm,15.09mm)(29.235mm,15.465mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (27.985mm,15.09mm)(27.985mm,15.465mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (29.235mm,14.715mm)(29.235mm,15.09mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (27.985mm,14.715mm)(27.985mm,15.09mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (22.9mm,-0.47mm)(22.9mm,19.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (22.9mm,19.73mm)(43.1mm,19.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.24mm < 0.254mm) Between Text "C31" (23.74mm,20.97mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (22.9mm,19.73mm)(43.1mm,19.73mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.24mm < 0.254mm) Between Text "C 31" (23.74mm,20.97mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (44.33mm,69.1mm)(44.33mm,69.5mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (45.13mm,69.1mm)(45.13mm,69.5mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (44.33mm,69.1mm)(44.33mm,69.5mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (45.13mm,69.1mm)(45.13mm,69.5mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (26.69mm,19.18mm)(26.69mm,19.58mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (27.49mm,19.18mm)(27.49mm,19.58mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (26.69mm,19.18mm)(26.69mm,19.58mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (27.49mm,19.18mm)(27.49mm,19.58mm) on Bottom Overlay And Pac

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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.24mm < 0.254mm) Between Track (31.36mm,20.34mm)(32.992mm,20.34mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (28.17mm,18.33mm)(28.17mm,18.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (28.97mm,18.33mm)(28.97mm,18.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (28.17mm,18.33mm)(28.17mm,18.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (28.97mm,18.33mm)(28.97mm,18.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Track (26.77mm, 16.35mm)(36.46mm, 100.82mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Track (36.46mm,98.92mm)(36.46mm,100.82mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Track (33.06mm,98.92mm)(33.06mm,100.82mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.2mm < 0.254mm) Between Track (33.06mm,98.92mm)(33.06mm,100.82mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (36.61mm,91.11mm)(36.61mm,92.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (36.635mm,92.745mm)(37.635mm,92.745mm) on Bottom Overlay And
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (36.61mm, 92.92mm)(37.635mm, 92.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (37.635mm,91.11mm)(37.635mm,92.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (36.61mm,91.11mm)(36.61mm,92.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (36.61mm,91.11mm)(37.635mm,91.11mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (37.635mm,91.11mm)(37.635mm,92.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.24mm < 0.254mm) Between Text "R40" (44.84mm,43.19mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (32.96mm,39.02mm)(32.96mm,39.42mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (33.76mm,39.02mm)(33.76mm,39.42mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (32.96mm,39.02mm)(32.96mm,39.42mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (33.76mm,39.02mm)(33.76mm,39.42mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (57.59mm, 40.08mm)(57.59mm, 40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (58.39mm, 40.08mm)(58.39mm, 40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (57.59mm,40.08mm)(57.59mm,40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (58.39mm,40.08mm)(58.39mm,40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (61.22mm, 40.08mm) (61.22mm, 40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (60.42mm, 40.08mm) (60.42mm, 40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (61.22mm,40.08mm)(61.22mm,40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (60.42mm,40.08mm)(60.42mm,40.48mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (61.85mm,40.09mm)(61.85mm,40.49mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (62.65mm, 40.09mm) (62.65mm, 40.49mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (61.85mm, 40.09mm)(61.85mm, 40.49mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (62.65mm, 40.09mm)(62.65mm, 40.49mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.234mm < 0.254mm) Between Text "C13" (48.02mm,66.39mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.18mm < 0.254mm) Between Text "C15" (31.51mm,65.5mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,52.53mm)(36.41mm,52.53mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,52.53mm)(36.41mm,52.53mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,51.73mm)(36.41mm,51.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,51.73mm)(36.41mm,51.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,52.53mm)(36.41mm,52.53mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,52.53mm)(36.41mm,52.53mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,51.73mm)(36.41mm,51.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.254mm) Between Track (36.31mm,51.73mm)(36.41mm,51.73mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (36.79mm,51.09mm)(37.19mm,51.09mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (36.79mm,50.29mm)(37.19mm,50.29mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (36.79mm,51.09mm)(37.19mm,51.09mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (36.79mm,50.29mm)(37.19mm,50.29mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (101.42mm,69.53mm)(101.82mm,69.53mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (101.42mm,70.33mm)(101.82mm,70.33mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (101.42mm,69.53mm)(101.82mm,69.53mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (101.42mm,70.33mm)(101.82mm,70.33mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (105.5mm,88.23mm)(105.9mm,88.23mm) on Bottom Overlay And Pac

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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (105.5mm,87.43mm)(105.9mm,87.43mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (105.5mm,88.23mm)(105.9mm,88.23mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (105.5mm,87.43mm)(105.9mm,87.43mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (83.05mm,99.12mm)(83.05mm,99.52mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (82.25mm,99.12mm)(82.25mm,99.52mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (83.05mm,99.12mm)(83.05mm,99.52mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (82.25mm,99.12mm)(82.25mm,99.52mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.15mm,102.04mm)(80.55mm,102.04mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.15mm,101.24mm)(80.55mm,101.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.15mm,102.04mm)(80.55mm,102.04mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (80.15mm,101.24mm)(80.55mm,101.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (22.163mm,101.725mm)(32.463mm,101.725mm) on Bottom Overlay Anc
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (24.15mm,91.35mm)(30.45mm,91.35mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (34.46mm,91.24mm)(34.86mm,91.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (34.46mm,90.44mm)(34.86mm,90.44mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (34.46mm,91.24mm)(34.86mm,91.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (34.46mm,90.44mm)(34.86mm,90.44mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.35mm,87.24mm)(20.75mm,87.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.35mm,88.04mm)(20.75mm,88.04mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.35mm,87.24mm)(20.75mm,87.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (20.35mm,88.04mm)(20.75mm,88.04mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (24.17mm,69.42mm)(24.57mm,69.42mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (24.17mm,70.22mm)(24.57mm,70.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (24.17mm,69.42mm)(24.57mm,69.42mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Track (24.17mm,70.22mm)(24.57mm,70.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (43.362mm,54.92mm)(44.187mm,55.745mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(43.362mm,54.92mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm) (34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac

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#### Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)

Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(34.887mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac

### Silk to Silk (Clearance=0.254mm) (AII),(AII)

Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Text "R22" (80.061mm,25.364mm) on Top Overlay And Arc (80.75mm,26.04mm) on Top Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Text "L3" (87.02mm,12.22mm) on Top Overlay And Arc (92.995mm,9.625mm) on Top Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Text "L5" (26.52mm,11.88mm) on Top Overlay And Arc (32.995mm,9.625mm) on Top Silk To Silk Clearance Constraint: (0.094mm < 0.254mm) Between Text "R40" (44.84mm,43.19mm) on Bottom Overlay And Arc (44.599mm,46.006mm) or Silk To Silk Clearance Constraint: (0.252mm < 0.254mm) Between Text "U3" (95.22mm,20.63mm) on Bottom Overlay And Arc (93.28mm,20.3mm) or

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